



# Bill of Materials

TI DESIGNS

TIDM-INDUCTIVEPROX

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	PCB1		Printed Circuit Board	Any				
2	2	C1, C3	150pF	CAP, CERM, 150 pF, 50 V, +/- 5%, COG/NP0, 0603	MuRata	GRM1885C1H151JA01D		0603	
3	1	C2	330pF	CAP, CERM, 330 pF, 50 V, +/- 1%, COG/NP0, 0603	TDK	C1608C0G1H331F080AA		0603	
4	1	CES1	0.47uF	CAP, CERM, 0.47 $\mu$ F, 10 V, +/- 10%, X5R, 0603	MuRata	GRM188R61A474KA61D		0603	
5	6	R1,R2,R3,R4,R5,R6	0 $\Omega$	RES, 0, 5%, 0.125 W, 0805	Panasonic	ERJ-6GEY0R00V		0805	
6	1	L1	470 $\mu$ H	Inductor, Drum Core, Ferrite, 470 $\mu$ H, 0.11 A, 14.3 ohm, SMD	Bourns	SDR0302-471KL		SDR0302	
7	1	J1		Header, 100mil, 3x2, Gold, TH	Sullins Connector Solutions	PBC03DAAN	-		
8	1	ESI		Connector Header, 100mil, 8x2, Gold, TH	Sullins Connector Solutions	SFH11-PBPC-D08-ST-BK			

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